

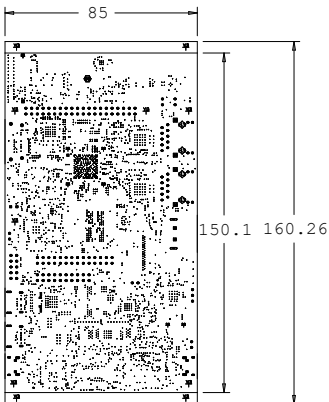
REVISIONS		
REV #	DESCRIPTION	DATE
REV #	CCN #	DDMMYY

FABRICATION NOTES:

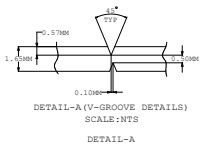
1. MATERIALS: PAPER IN ACCORDANCE WITH IPC-6012, CLASS 2; FOR IPC-6011, PCB SHALL BE MANUFACTURED USING TFRG IT 180A OR EQUIVALENT.
2. FABRICATE:
1. LAMINATE AND PREPRESS (2-STAGE) TO BE IN ACCORDANCE WITH IPC-6011/126.  
(MIN.TE 170)
  2. BOARD WEIGHT TO BE IN ACCORDANCE WITH IPC-6016-150, UNLESS OTHERWISE SPECIFIED.
  3. ACCEPTED WEIGHT FOR INNER SIGNAL LAYERS AND INNER PATTERN LAYERS TO BE 30M (10.1).  
FOR OTHER LAYERS 30M (1.02). COVER WEIGHT 18 TO BE CONSIDERED "FINISHED".
  4. THE COVERED TOLL THICKNESS TOLERANCES SHALL BE AS PER IPC-6012 PART NO.3-7 AND 3-8.
  5. ALL HOLES SHALL BE LOCATED WITHIN 0.15MM DIRECTION OF THEIR POSITION.  
LAYERS TO LAYER DISCREPANCY SHALL BE WITHIN 0.125MM.
  6. BOM AND TWIST SHALL NOT EXCEED MORE THAN 0.75% OF THE DESIGN LENGTH.
  7. CONDUCTOR WIDTH SHALL NOT BE LESS THAN 20% FROM ITS ORIGINAL DATA. INCASE FOR MATCHING REQUIREMENT, NEUTRAL SHALL APPROVE THE MODIFIED WIDTHS AND LENGTHS.
  8. TRACK WIDTH SHALL BE MEASURED ON THE SURFACE IN CONTACT WITH THE LAMINATE.
  9. BOARD WEIGHT SHALL BE ACCORDING TO IPC-6012 CLASS 2.
  10. AUTOMATED OPTICAL INSPECTION OF ALL THE LAYERS IS REQUIRED.
3. FINISH:
1. ALL EXPOSED CONDUCTIVE PATTERN AREAS NOT COVERED WITH SOLDER MASK OR OTHER PLATING SHALL BE ENIT, ELECTROLESS NICKEL/IMMERSION GOLD. ELECTROLESS NICKEL SHALL BE 3-6MICRONS, TYPICAL IMMERSION GOLD SHALL BE 0.05-0.08 MICRONS OF SOLUBLE/INSOLUBLE IMMERSION GOLD.
  2. APPLY LIQUID HOT IMAGINABLE SOLDER MASK PER IPC-3M-84.40, CLASS H, TO BOTH SIDES OF THE BOARD OVER BARE COPPER. THE COVERAGE SHALL BE 100% AND THE THICKNESS SHALL BE 1.5-2.5 MICRONS. THE FINISH PAGES THAT ARE 0.06(0.003) PER SIDE SHALL BE REDUCED IF REQUIRED, HOWEVER, ALLOW OF SOLDER MASK SHALL BE GREEN.
  3. FILLSHOWN SHALL BE WHITE, PERMANENT, ORGANIC, NON-CONDUCTIVE INK. THERE SHALL BE NO SINKHOLES OR ANY SOLUBLE COMPONENT PAKE. CLIPPING OF FILM SCREEN SHALL BE ALLOWED ON THE FILM SCREEN FALLS OR SOLUBLE AREAS.
  4. SURFACE AND VIA ROLLS FINISH SHALL NOT BE LESS THAN 20M (0.00079). INCASE OF LAGER THAN 20M (0.00079) VIA SHALL BE 10M (0.00039) AND 10M (0.00039) SHALL NOT BE LESS THAN 15M (0.0006").
  5. ALL HOLES SUBROCESSED BY LAND -0.010" SHALL BE COMPLIANCE TO IPC6012, CLASS 2.
9. MARKING:
1. BOARD SHALL MEET THE REQUIREMENTS OF US-78 WITH FLAMMABILITY RATING OF MINIMUM 94V-0. UL LOGO, MANUFACTURER'S IDENTIFICATION AND DATE CODE LETTER SHALL BE RENDERED IN SILKSCREEN.
10. TEST REQUIREMENTS:
1. I/OA TEST LIST ELECTRICAL VERIFICATION USING MISTRAL SUPPLIED IPC-6013-356 SET LIST FOR OPEN AND SHORTS.
  2. TRIVING IS ALLOWED ONLY IN THE PANEL FRAME, NOT IN THE CIRCUIT AREA.
  3. TRAP SHOPS SHALL BE OPENED ON VIA'S AND THROUGH HOLE PADS IN ALL INTERNAL AND OUTER LAYERS.
  4. ALL CONDUCTORS SHALL BE SOLDERED IF REQUIRED.
  5. ALL CONDUCTORS SHALL BE SOLDERED IF REQUIRED.
  6. FINISHED PCB THICKNESS SHALL BE 0.562" +/- 0.004".
  7. MIN. TENSILE TENSILE/SPACING ON BOARD IS 0.0032"/0.003".
  8. INSURE I/OA REQUIRED 8-PIN HOMER SHALL BE PROVIDED FOR THE PCB SILKSCREEN.
  9. VIA ON PAD SHALL BE FULLY FILLED.


S/L	TYPE	LAYER	TRACEWIDTH (MILs)	SPACING (MILs)	IMPEDANCE (Ohms)	REF. LAYER
01	DRG COUPLED STRIPLINE	P5.1, P10	2.75	2.75	50	Z14, Z17, Z18
02	DRG COUPLED MICROSTRIP	P5.1, P10	2.75	2.75	100	Z14, Z17, Z18
03	DRG COUPLED MICROSTRIP	P1.1, P6	1.7	1.7	80	Z14, Z17, Z18
04	DRG COUPLED MICROSTRIP	P1.1, P6	1.7	1.7	80	Z14, Z17, Z18
05	DRG COUPLED MICROSTRIP	P1.1, P6	1.7	1.7	80	Z14, Z17, Z18
06	DRG COUPLED MICROSTRIP	L1, L10	6.02	6.02	80	Z19
07	DRG STRIPLINE	P1.1, P6	9.05	NA	50	Z14, Z17, Z18
08	MICROSTRIP	P1.1, P10	9.05	NA	50	Z14, Z17, Z18
09	MICROSTRIP	P1.1, P6	1.6	NA	50	Z14, Z17, Z18
10	MICROSTRIP	P1.1, P6	1.6	NA	50	Z14, Z17, Z18

LAYER NAME	FINISHED Cu	X-SECTION	DIELECTRIC THICKNESS
PRIMARY SIDE SILKSCREEN			[INCHES]
PRIMARY SIDE GOLDMASK			
101 PRIMARY SIDE	100%		0.0037
102 GROUND-PLANE-1	100%		0.002
103 INNER-SIGNAL-1	100%		0.0066
104 GROUND-PLANE-2	100%		0.005
105 POWER-PLANE-1	100%		0.009
106 POWER-PLANE-2	100%		0.005
107 GROUND-PLANE-3	100%		0.006
108 INNER-SIGNAL-2	100%		0.004
109 GROUND-PLANE-4	100%		0.0037
110 SECONDARY SIDE	100%		
SECONDARY SIDE GOLDMASK			
SECONDARY SIDE SILKSCREEN			



DRILL CHART: TOP TO BOTTOM						
ALL UNITS ARE IN MILS						
FIGURE	FINISHED SIZE	TOLERANCE	DRILL	TOLERANCE	TRAVEL	QTY
•	22.0	+3.0/-3.0	—	PLATED	27.68	
•	36.0	+3.0/-3.0	—	PLATED	18	
•	40.0	+3.0/-2.0	—	PLATED	10	
•	42.0	+3.0/-3.0	—	PLATED	4	
•	52.0	+1.0/-1.0	—	PLATED	6	
•	62.0	+3.0/-3.0	—	PLATED	6	
•	118.0	+2.0/-2.0	—	PLATED	2	
•	33.0	+2.0/-2.0	—	NON-PLATED	2	
•	33.0	+3.0/-3.0	—	NON-PLATED	6	
•	34.0	+1.0/-2.0	—	NON-PLATED	1	
•	44.0	+2.0/-2.0	—	NON-PLATED	1	
•	48.0	+3.0/-3.0	—	NON-PLATED	2	
•	62.0	+2.0/-2.0	—	NON-PLATED	1	
•	62.0	+3.0/-3.0	—	NON-PLATED	6	
•	108.0	+3.0/-3.0	—	NON-PLATED	10	
◆	126.0	+3.0/-3.0	—	NON-PLATED	6	
•	62.0x24.0	+3.0/-2.0	+3.0/-3.0	PLATED	6	
•	62.0x24.0	+2.0/-2.0	+2.0/-2.0	PLATED	6	
•	68.0x14.0	+3.0/-3.0	+3.0/-3.0	PLATED	6	
•	62.0x24.0	+3.0/-2.0	+2.0/-2.0	PLATED	6	
•	118.0x24.0	+3.0/-3.0	+2.0/-2.0	PLATED	6	



SIGNATURES		DATE		 TEXAS INSTRUMENTS	FROC142B
LAYOUT BY MK		241125			
REVIEWED BY UD		241125			
APPROVED BY AMB		241125			
AM62x EVM BOARD					
		SIZE D		Rev B	
SCALE:NONE				SHEET 1 OF 17	